

General Description

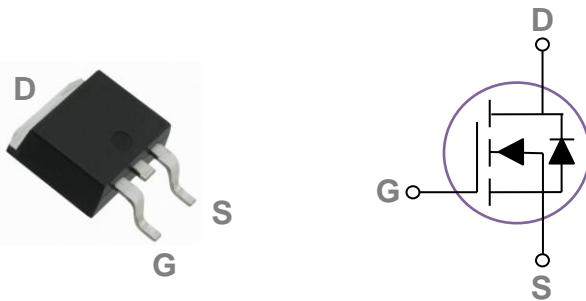
These N-Channel enhancement mode power field effect transistors are using Super Junction technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply

| BVDSS | RDS(ON) | ID |
|-------|---------|----|
| 600V | 1.2Ω | 4A |

Features

- 4A, 600V, RDS(ON) = 1.2Ω@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

TO252 Pin Configuration



Applications

- High efficient switched mode power supplies
- LED Lighting
- Adapter/charger

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|------------------|---|------------|-------|
| Vds | Drain-Source Voltage | 600 | V |
| Vgs | Gate-Source Voltage | ±30 | V |
| I _D | Drain Current – Continuous (Tc=25°C) | 4 | A |
| | Drain Current – Continuous (Tc=100°C) | 2.53 | A |
| I _{DM} | Drain Current – Pulsed ¹ | 16 | A |
| EAS | Single Pulse Avalanche Energy ² | 42 | mJ |
| I _{AS} | Single Pulse Avalanche Current ² | 2.9 | A |
| P _D | Power Dissipation (Tc=25°C) | 28.4 | W |
| | Power Dissipation – Derate above 25°C | 0.23 | W/°C |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction to ambient | --- | 62 | °C/W |
| R _{θJC} | Thermal Resistance Junction to Case | --- | 4.4 | °C/W |



600V N-Channel MOSFETs

PJD04N60D

Electrical Characteristics (T_J=25 °C, unless otherwise noted)**Off Characteristics**

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|---|--|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 600 | --- | --- | V |
| △BV _{DSS} /△T _J | BV _{DSS} Temperature Coefficient | Reference to 25°C, I _D =1mA | --- | 0.52 | --- | V/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =600V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±30V, V _{DS} =0V | --- | --- | ±100 | nA |

On Characteristics

| | | | | | | |
|----------------------|---|--|-----|------|-----|-------|
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =10V, I _D =2A | --- | 1 | 1.2 | Ω |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250μA | 2 | --- | 4 | V |
| △V _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | -7.7 | --- | mV/°C |

Dynamic and switching Characteristics

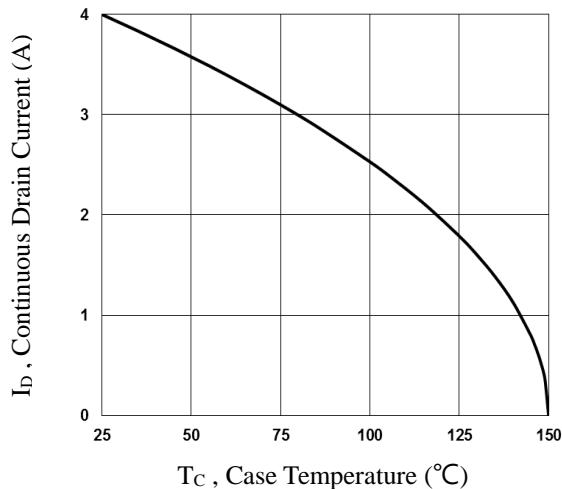
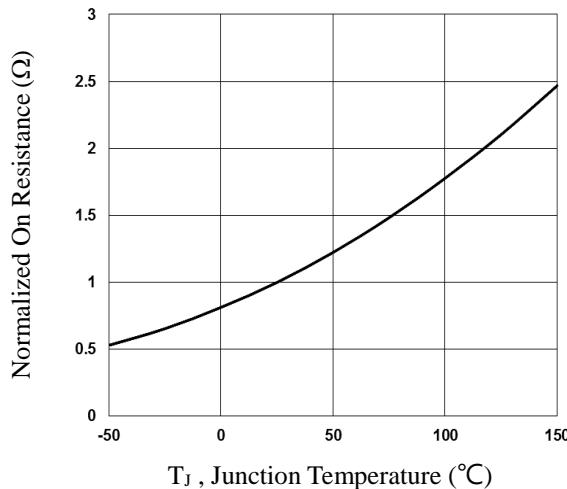
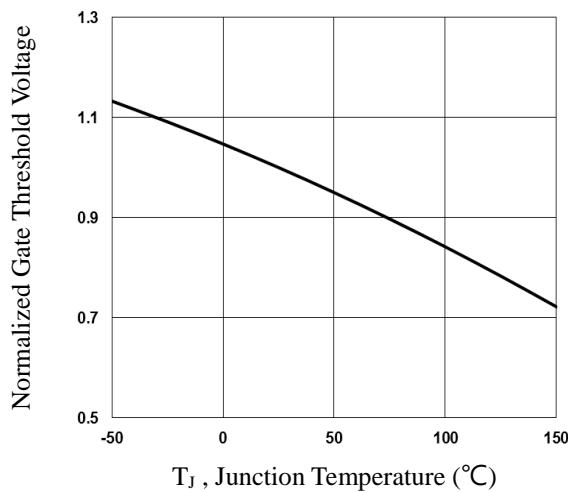
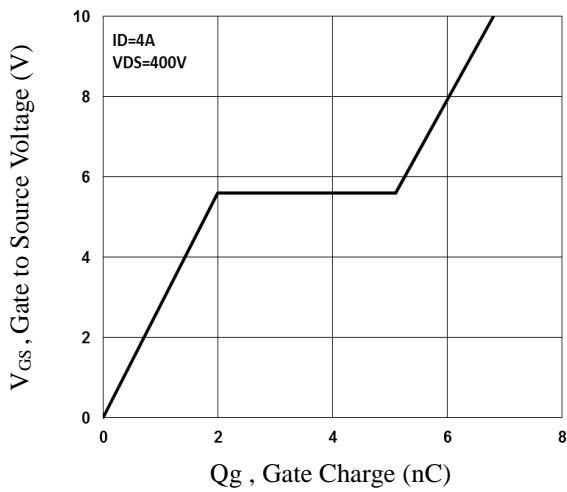
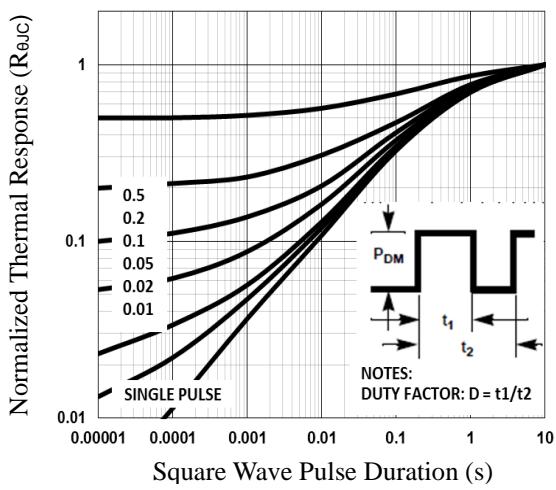
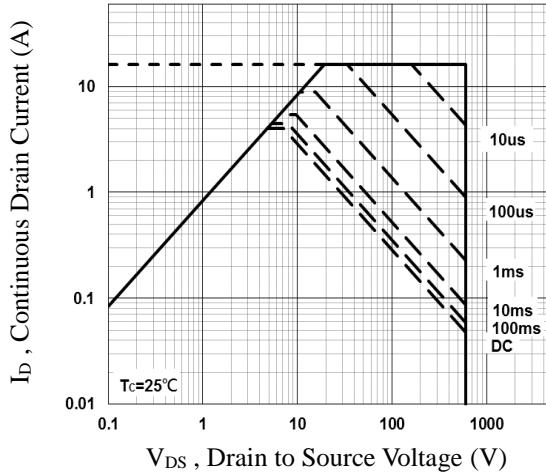
| | | | | | | |
|---------------------|------------------------------------|---|-----|------|-----|----|
| Q _g | Total Gate Charge ^{2,3} | V _{DS} =400V, V _{GS} =10V, I _D =4A | --- | 6.8 | --- | nC |
| Q _{gs} | Gate-Source Charge ^{2,3} | | --- | 2 | --- | |
| Q _{gd} | Gate-Drain Charge ^{2,3} | | --- | 3.1 | --- | |
| T _{d(on)} | Turn-On Delay Time ^{2,3} | V _{DD} =380V, V _{GS} =10V, R _G =25Ω I _D =11A | --- | 32.6 | --- | ns |
| T _r | Rise Time ^{2,3} | | --- | 18.4 | --- | |
| T _{d(off)} | Turn-Off Delay Time ^{2,3} | | --- | 59.6 | --- | |
| T _f | Fall Time ^{2,3} | | --- | 30 | --- | |
| C _{iss} | Input Capacitance | V _{DS} =25V, V _{GS} =0V, F=1MHz | --- | 283 | --- | pF |
| C _{oss} | Output Capacitance | | --- | 142 | --- | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 2.8 | --- | |

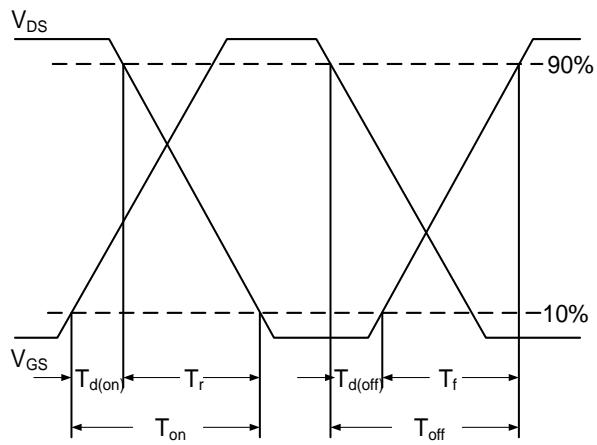
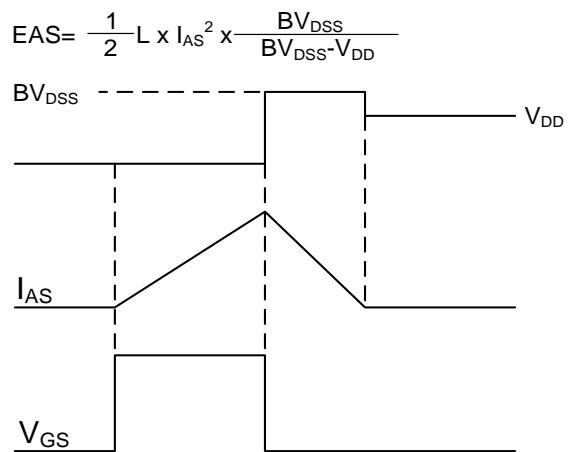
Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------------|--------------------------------------|--|------|-------|------|------|
| I _s | Continuous Source Current | V _G =V _D =0V, Force Current | --- | --- | 4 | A |
| I _{SM} | Pulsed Source Current | | --- | --- | 8 | A |
| V _{SD} | Diode Forward Voltage | V _{GS} =0V, I _s =11A, T _J =25°C | --- | --- | 1.3 | V |
| t _{rr} | Reverse Recovery Time ² | V _{GS} =0V, I _s =4A, dI/dt=100A/μs, T _J =25°C | --- | 157.6 | --- | ns |
| Q _{rr} | Reverse Recovery Charge ² | | --- | 1.06 | --- | uC |
| I _{rrm} | Peak reverse recovery current | T _J =25°C | --- | 11.3 | --- | A |

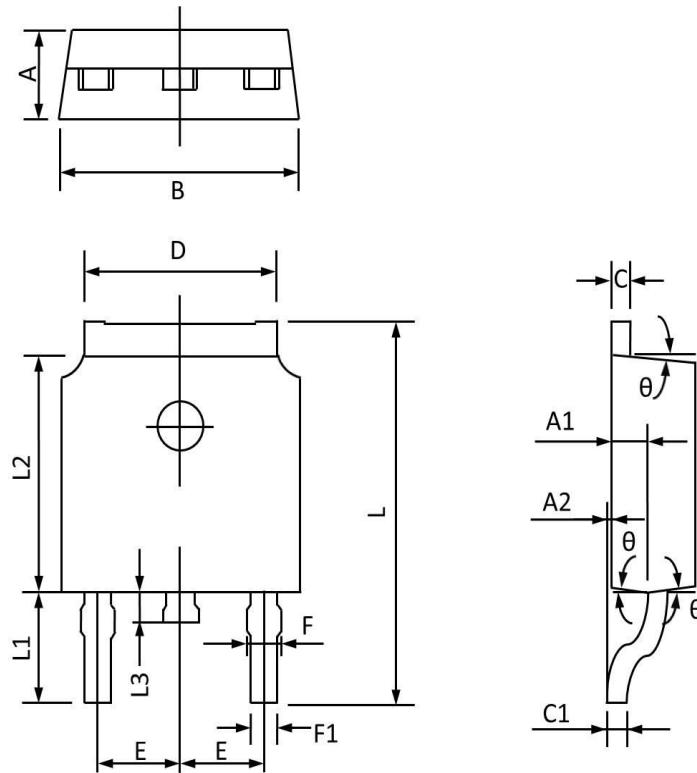
Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- V_{DD}=50V, V_{GS}=10V, L=10mH, I_{AS}=2.9A., R_G=25Ω, Starting T_J=25°C.
- The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
- Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_c

Fig.2 Normalized $R_{DS(on)}$ vs. T_j

Fig.3 Normalized V_{th} vs. T_j

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 EAS Waveform

TO252 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | MAX | MIN | MAX | MIN |
| A | 2.400 | 2.200 | 0.094 | 0.087 |
| A1 | 1.110 | 0.910 | 0.044 | 0.036 |
| A2 | 0.150 | 0.000 | 0.006 | 0.000 |
| B | 6.800 | 6.400 | 0.268 | 0.252 |
| C | 0.580 | 0.450 | 0.023 | 0.018 |
| C1 | 0.580 | 0.460 | 0.023 | 0.018 |
| D | 5.500 | 5.100 | 0.217 | 0.201 |
| E | 2.386 | 2.186 | 0.094 | 0.086 |
| F | 0.940 | 0.600 | 0.037 | 0.024 |
| F1 | 0.860 | 0.500 | 0.034 | 0.020 |
| L | 10.400 | 9.400 | 0.409 | 0.370 |
| L1 | 3.000 | 2.400 | 0.118 | 0.094 |
| L2 | 6.200 | 5.400 | 0.244 | 0.213 |
| L3 | 1.200 | 0.600 | 0.047 | 0.024 |
| θ | 9° | 3° | 9° | 3° |